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Switching

SP8M3

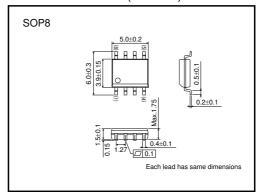
● Features

- 1) Low on-resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small and Surface Mount Package (SOP8).

Application

Power switching, DC / DC converter.

●External dimensions (Unit : mm)

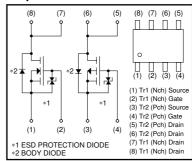


● Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Lin	Unit		
		Symbol	Nchannel	Pchannel	Offit	
Drain-source voltage		V _{DSS}	30	-30	V	
Gate-source voltage		Vgss	20	20 –20		
Drain current	Continuous	I _D	I _D ±5.0 ±4.5		Α	
	Pulsed	IDP	±20	±18	Α	*1
Source current	Continuous	Is	1.6	-1.6	Α	
(Body diode)	Pulsed	Isp	20	-18	Α	*1
Total power dissipation		PD	2		W	*2
Channel temperature		Tch	150		°C	
Storage temperature		Tstg	-55 to +150		°C	

^{*1} Pw≤10μs, Duty cycle≤1% *2 MOUNTED ON A CERAMIC BOARD.

●Equivalent circuit



*A protection diode is included between the gate and the source terminals to protect the diode against static electricity when the product is in use. Use the protection circuit when the fixed voltages are exceeded.

●Thermal resistance (Ta=25°C)

Parameter	Symbol	Limits	Unit		
Channel to ambient	Rth (ch-a)	62.5	°C / W *		

*MOUNTED ON A CERAMIC BOARD.

N-ch

●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	_
Gate-source leakage	Igss	-	_	10	μA	Vgs=20V, Vps=0V	_
Drain-source breakdown voltage	V _{(BR) DSS}	30	_	_	٧	I _D =1mA, V _{GS} =0V	
Zero gate voltage drain current	IDSS	_	_	1	μΑ	V _{DS} =30V, V _{GS} =0V	_
Gate threshold voltage	V _{GS (th)}	1.0	_	2.5	٧	V _{DS} =10V, I _D =1mA	_
		-	36	51		I _D =5.0A, V _{GS} =10V	*
Static drain-source on-state resistance	R _{DS (on)}	-	52	73	mΩ	I _D =5.0A, V _{GS} =4.5V	*
resistance		-	58	82		I _D =5.0A, V _{GS} =4V	*
Forward transfer admittance	Yfs	3.0	_	_	S	I _D =5.0A, V _{DS} =10V	*
Input capacitance	Ciss	_	230	_	pF	V _{DS} =10V	
Output capacitance	Coss	_	80	_	pF	V _G S=0V	
Reverse transfer capacitance	Crss	_	50	_	pF	f=1MHz	
Turn-on delay time	t _{d (on)}	-	6	_	ns	I _D =2.5A, V _{DD} ≒15V	*
Rise time	tr	-	8	_	ns	V _{GS} =10V	*
Turn-off delay time	td (off)	_	22	_	ns	R _L =6.0Ω	*
Fall time	tf	-	5	_	ns	R _G =10Ω	*
Total gate charge	Qg	-	3.9	5.5	nC	V _{DD} ≒15V	*
Gate-source charge	Qgs	_	1.1	_	nC	V _{GS} =5V	*
Gate-drain charge	Q _{gd}	_	1.4	_	nC	I _D =5.0A	*

^{*}Pulsed

●Body diode characteristics (Source-Drain Characteristics) (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Forward voltage	VsD	_	_	1.2	V	Is=6.4A, V _G s=0V	*

^{*}Pulsed

P-ch

●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Gate-source leakage	Igss	-	-	-10	μΑ	Vgs= -20V, Vps=0V	
Drain-source breakdown voltage	$V_{(BR)\;DSS}$	-30	_	_	٧	I _D = -1mA, V _{GS} =0V	
Zero gate voltage drain current	I _{DSS}	_	_	-1	μΑ	V _{DS} =-30V, V _{GS} =0V	
Gate threshold voltage	V _{GS (th)}	-1.0	_	-2.5	V	$V_{DS} = -10V$, $I_{D} = -1mA$	
		_	40	56		I _D = -4.5A, V _G S= -10V	*
Static drain-source on-state resistance	R _{DS (on)}	_	57	80	mΩ	I _D = -2.5A, V _G S= -4.5V	*
resistance		_	65	90		I _D = -2.5A, V _G S= -4.0V	*
Forward transfer admittance	Yfs	3.5	_	_	S	I _D = -2.5A, V _D S= -10V	*
Input capacitance	Ciss	_	850	_	pF	V _{DS} = -10V	
Output capacitance	Coss	_	190	_	pF	V _{GS} =0V	
Reverse transfer capacitance	Crss	-	120	-	pF	f=1MHz	
Turn-on delay time	t _{d (on)}	_	10	_	ns	I _D = −2.5A, V _{DD} ≒ −15V	*
Rise time	tr	_	25	_	ns	V _{GS} = -10V	*
Turn-off delay time	t _{d (off)}	_	60	_	ns	R _L =6.0Ω	*
Fall time	tf	_	25	_	ns	R _G =10Ω	*
Total gate charge	Qg	_	8.5	-	nC	V _{DD} ≒ –15V	*
Gate-source charge	Qgs	-	2.5	_	nC	V _{GS} = -5V	*
Gate-drain charge	Q _{gd}	_	3.0	_	nC	I _D = -4.5A	*

^{*}Pulsed

●Body diode characteristics (Source-Drain Characteristics) (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Forward voltage	VsD	_	_	-1.2	V	Is=-1.6A, Vgs=0V	*

^{*}Pulsed

N-ch

Electrical characteristic curves

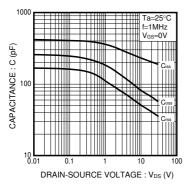


Fig.1 Typical Capacitance vs. Drain-Source Voltage

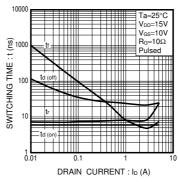


Fig.2 Switching Characteristics

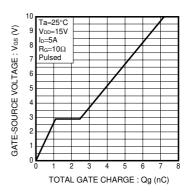


Fig.3 Dynamic Input Characteristics

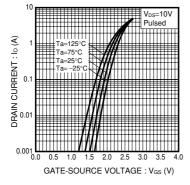


Fig.4 Typical Transfer Characteristics

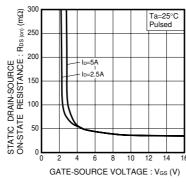


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

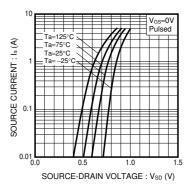


Fig.6 Source Current vs. Source-Drain Voltage

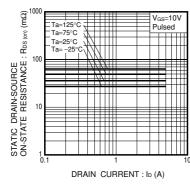


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (I)

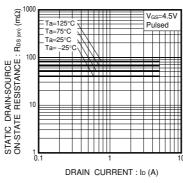


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (II)

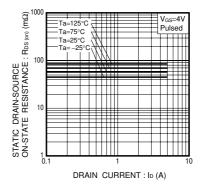


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (III)

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Electrical characteristic curves

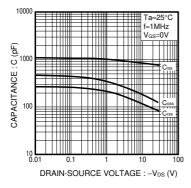


Fig.1 Typical Capacitance vs. Drain-Source Voltage

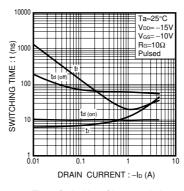


Fig.2 Switching Characteristics

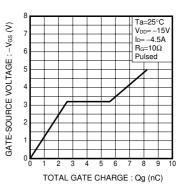


Fig.3 Dynamic Input Characteristics

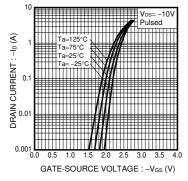


Fig.4 Typical Transfer Characteristics

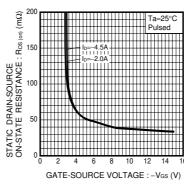


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

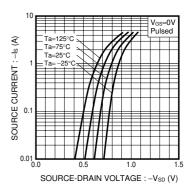


Fig.6 Source Current vs. Source-Drain Voltage

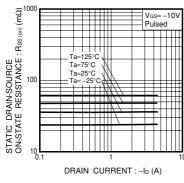


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (I)

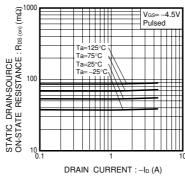


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (II)

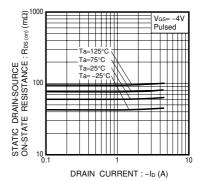


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (III)

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